

## P-Ch 20V Fast Switching MOSFETs

### Features:

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

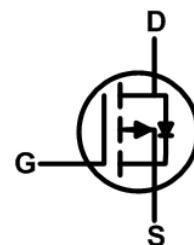
### SOT23S Pin Configurations



### Description:

The KWUC2601 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KWUC2601 meet the RoHS and Green Product requirement with full function reliability approved.



### Product Summary



BVDSS	RDS(on)	ID
-20V	60mΩ	-3.4A

### Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V <sub>DS</sub>	Drain-Source Voltage		-20	V
V <sub>GS</sub>	Gate-Source Voltage		±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-3.9	-3.4	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	-3.1	-2.7	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>		-14	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.32	1	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>3</sup>	0.84	0.64	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150		°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	125	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	95	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	80	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D=-1\text{mA}$	---	-0.014	---	$\text{V}/{}^{\circ}\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-4.5\text{V}$ , $I_D=-4\text{A}$	---	50	60	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$ , $I_D=-3\text{A}$	---	60	80	
		$V_{GS}=-1.8\text{V}$ , $I_D=-2\text{A}$	---	82	100	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	-0.35	-0.6	-1.0	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	3.95	---	$\text{mV}/{}^{\circ}\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-16\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	$\text{uA}$
		$V_{DS}=-16\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55\text{ }^{\circ}\text{C}$	---	---	-5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 12\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-3\text{A}$	---	12.8	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-15\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	10.2	---	nC
$Q_{gs}$	Gate-Source Charge		---	1.89	---	
$Q_{gd}$	Gate-Drain Charge		---	3.1	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-10\text{V}$ , $V_{GS}=-4.5\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	5.6	---	ns
$T_r$	Rise Time		---	40.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	33.6	---	
$T_f$	Fall Time		---	18	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	857	---	pF
$C_{oss}$	Output Capacitance		---	114	---	
$C_{rss}$	Reverse Transfer Capacitance		---	108	---	

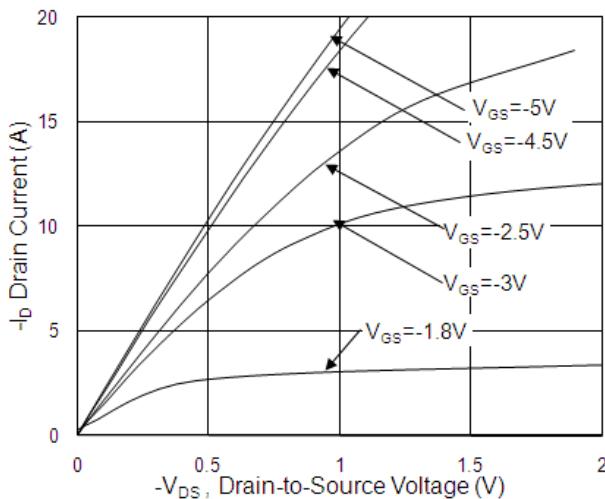
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3.4	A
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	-14	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V

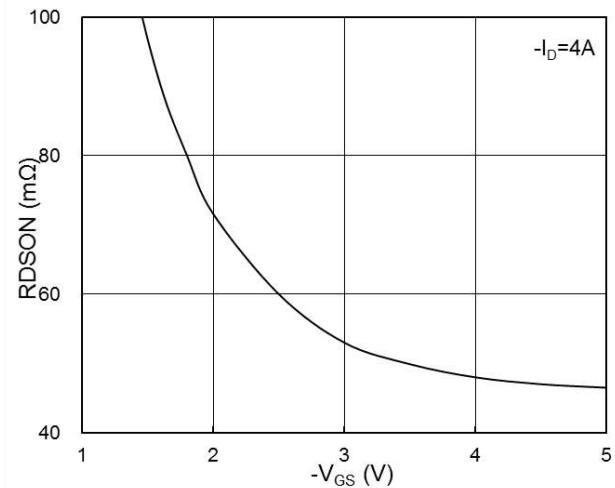
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150\text{ }^{\circ}\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.

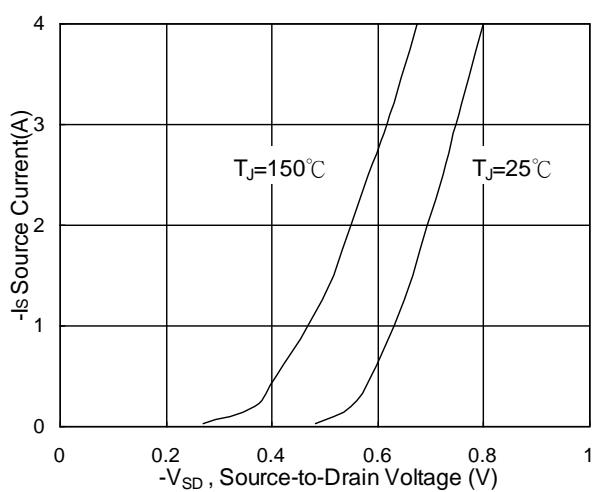
### Typical Characteristics



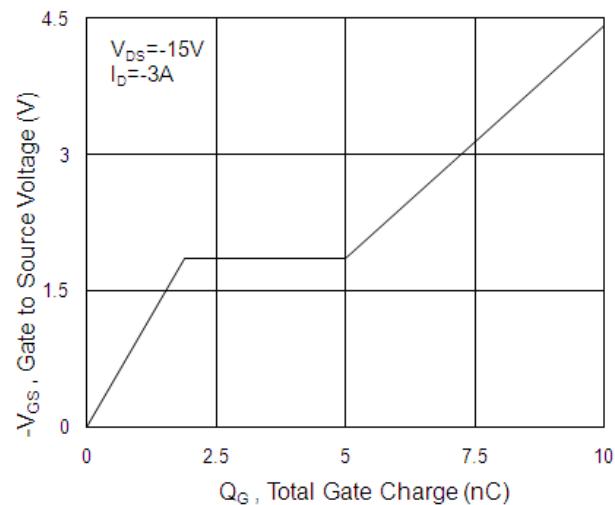
**Fig.1 Typical Output Characteristics**



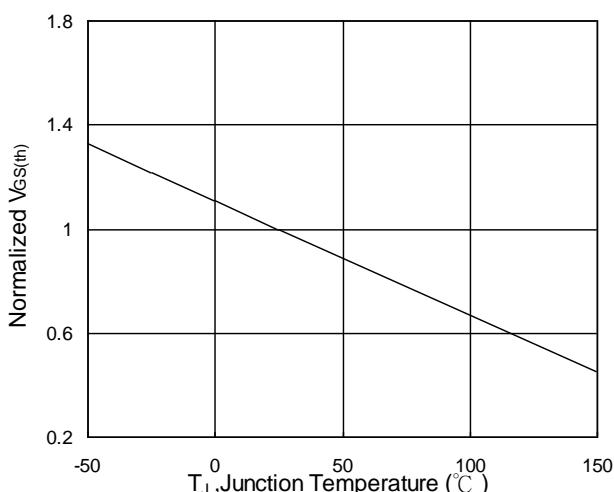
**Fig.2 On-Resistance vs. G-S Voltage**



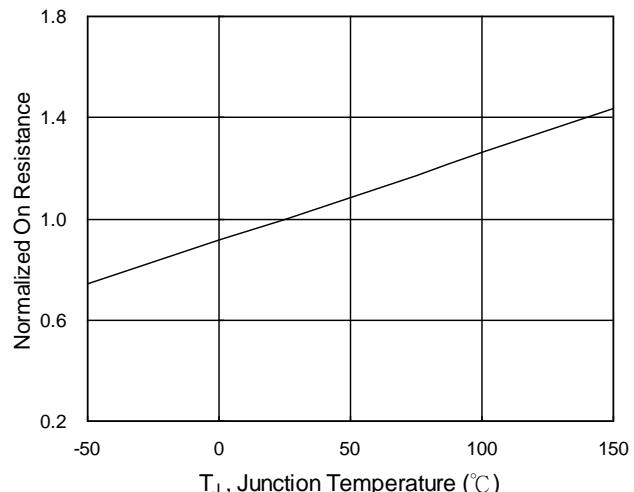
**Fig.3 Forward Characteristics of Reverse**



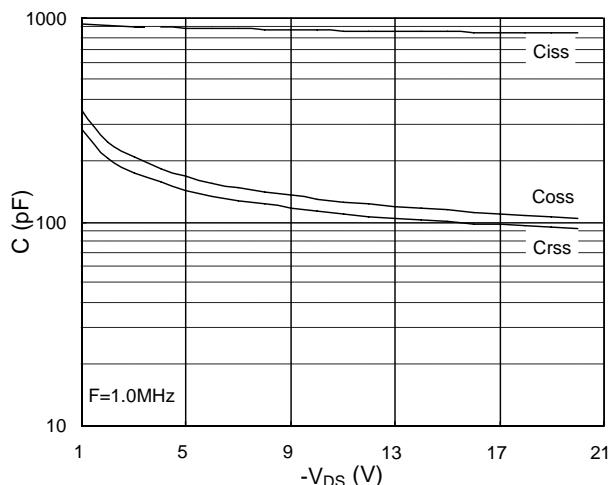
**Fig.4 Gate-charge Characteristics**



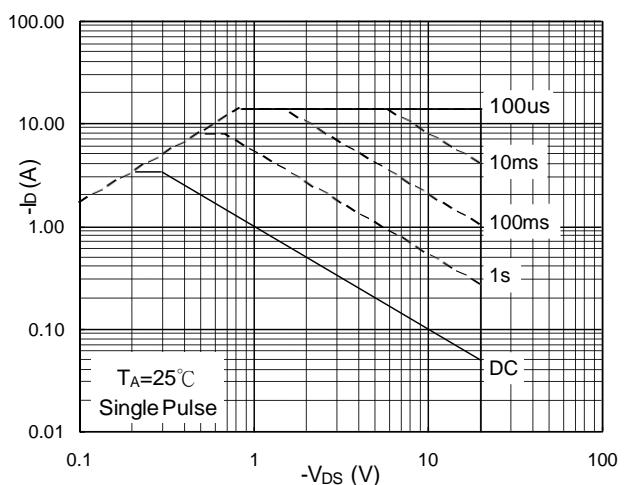
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



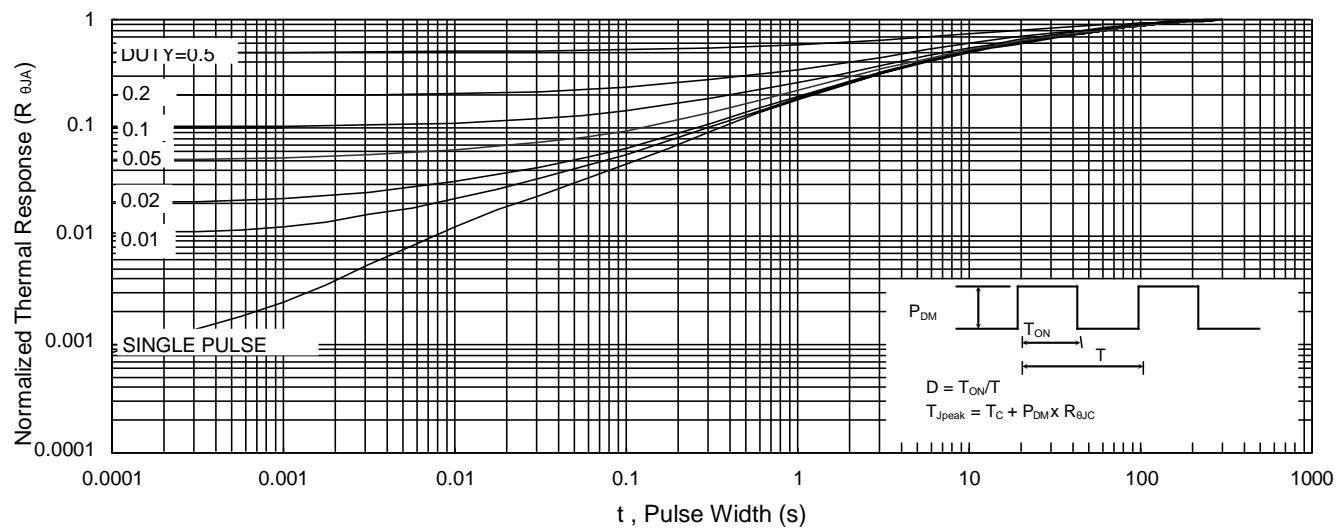
**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**



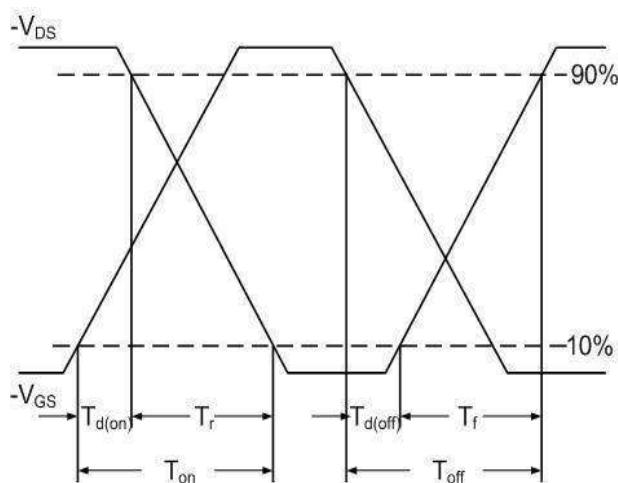
**Fig.7 Capacitance**



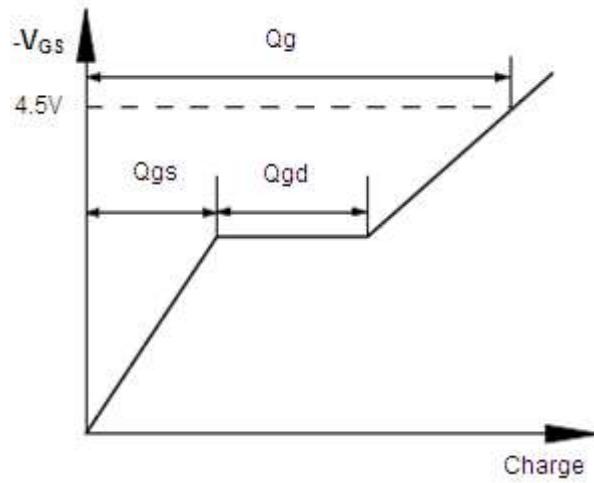
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

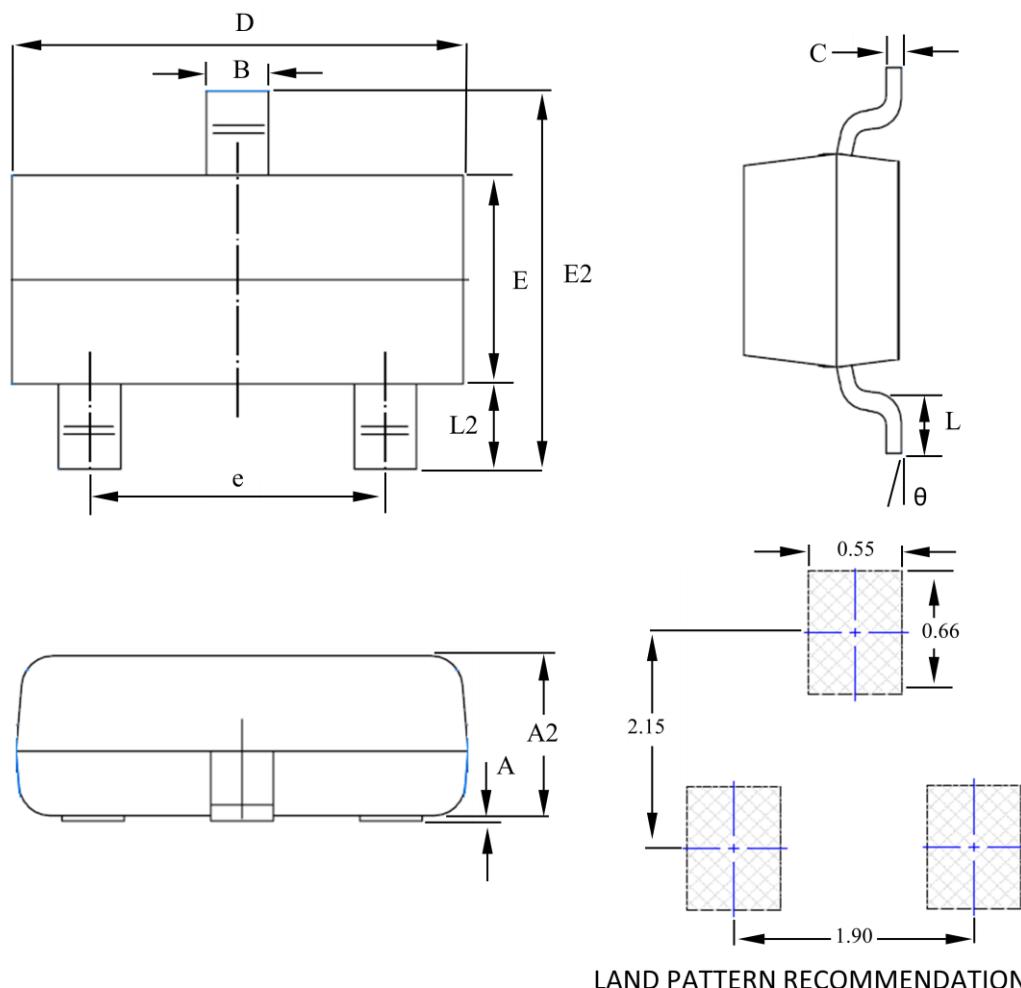


**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

## SOT-23S Package Outline



LAND PATTERN RECOMMENDATION

SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.00	--	0.10	0.000	--	0.004
A2	0.90	--	1.10	0.035	--	0.041
B	0.30	--	0.50	0.012	--	0.020
C	0.08	--	0.15	0.003	--	0.006
D	2.80	--	3.00	0.110	--	0.118
E	1.20	--	1.40	0.047	--	0.055
E2	2.25	--	2.55	0.089	--	0.100
L	0.30	--	0.50	0.012	--	0.020
L2	0.50	--	0.60	0.020	--	0.024
θ	0°	--	8°	0°	--	8°
e	1.80	--	2.00	0.071	--	0.079